Electrolytic Nickel Gold

Versatile Nickel-Gold Solutions

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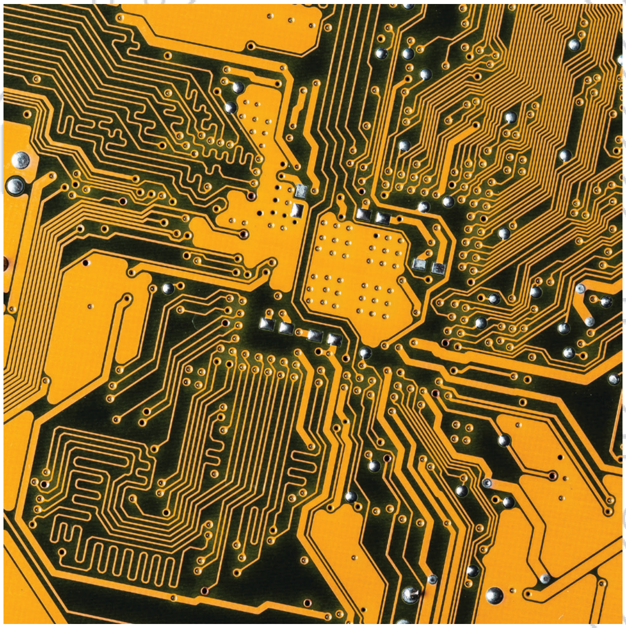
Orostrike C
Techni 434 HS - Soft Gold
Orosene 80 RC Hard Gold

Nickel-gold plating offers a wide array of specifications, grades, and applications, making it versatile and suitable for a broad range of uses. Technic has long specialized in gold electroplating processes, offering a comprehensive range of options tailored for PCB applications.



Primary advantages include:

Corrosion Resistance: Excellent corrosion resistance, ensuring durability in various environments.

Wear Resistance: The hardness of the nickel-gold alloy provides resistance to wear and abrasion, extending the lifespan of plated components.

Electrical Conductivity: Gold's conductivity ensures good performance in applications where electrical conductivity is essential.

Solderability: The gold layer creates a solderable surface, making it suitable for electronic components and soldering processes.

Features

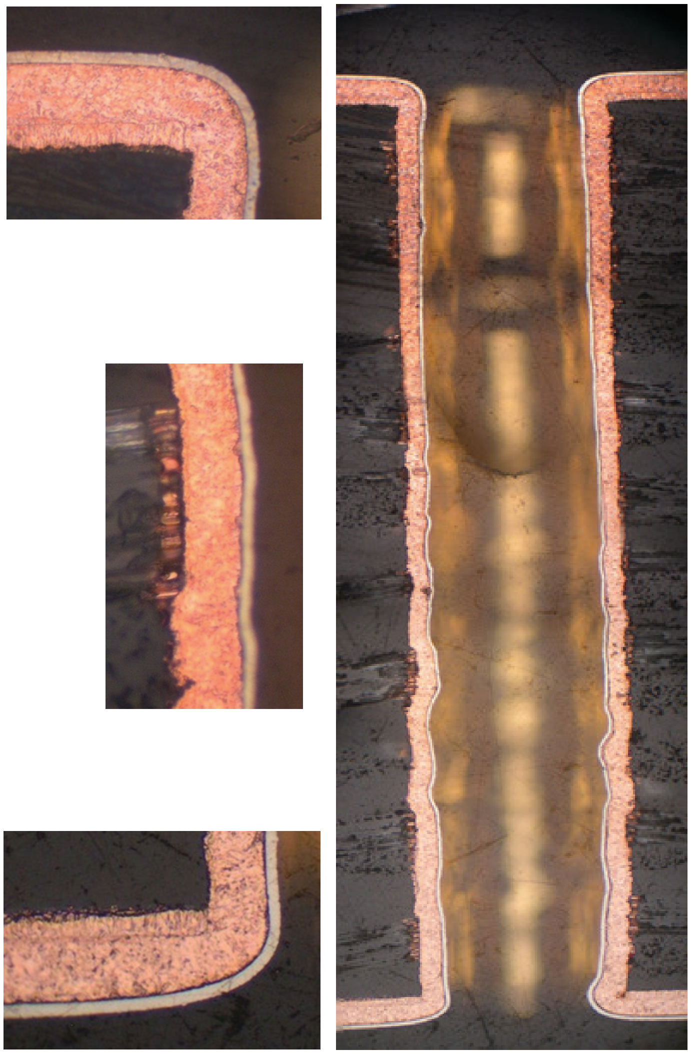
- Ideal for high volume production
- Excellent adhesion and distribution
- Exceptional physical properties
- For use in high aspect ratios holes or microvias

Benefits

- Unsurpassed reliability
- Proven technology
- Reduced cost with enhanced distribution
- Long bath life
- Relyable/consistent coverage

Technic MP200 - Advanced roll-to-roll wet processing system that offers a variety of key benefits for today's flexible printed circuits, metal foils, and other flexible substrates.

Electrolytic Nickel-Gold Products



HT2 Nickel

- Available in Sulfate or Sulfamate forms.
- Utilizes a High Throw formulation to enhance through-hole distribution and aspect ratio.
- Improves distribution significantly compared to other nickel processes.
- Low-stress characteristics.

Orostrike C

- Facilitates intimate adhesion of gold onto nickel surfaces.
- Recommended for both Soft and Hard Gold applications.
- Enhances gold performance in porosity testing.
- Compatible with various gold baths.

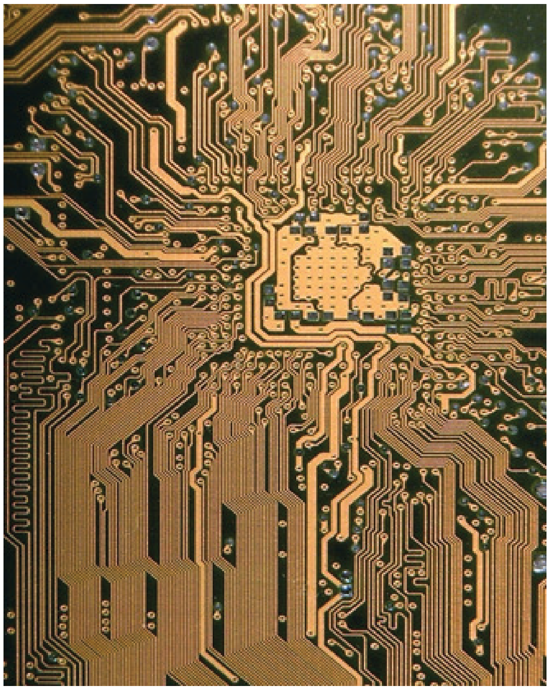
Techni 434 Soft Gold

- Offers a pure gold process suitable for gold wire bonding and solderability applications.
- High purity and fine-grain deposit.
- Meets MIL-G-45204C specifications, Type III, Grade A.
- Gold purity exceeds 99.9%, with hardness between 80-90 Knoop.

Orosene 80 RC Hard Gold

- Industry-leading High-Speed Hard Gold for PCB Applications.
- Features cobalt-brightened deposit conforming to ASTM B488-01, Type I & II, Grade C.
- Provides uniform appearance and consistent physical properties.
- Gold purity surpasses 99.7%, with hardness between 140-170 Knoop.

These processes offer comprehensive options for nickel and gold plating applications, meeting industry standards and delivering exceptional performance characteristics.



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